6.2mm Diameter Round Terminal (Radial Type)

Round terminal type with excellent PC board mounting performance





■ Typical Specifications

Items	Specifications
Rating (max.)	50mA 12V DC
Rating (min.)	10μA 1V DC
Initial contact resistance	500mΩ max.
Travel (mm)	0.25

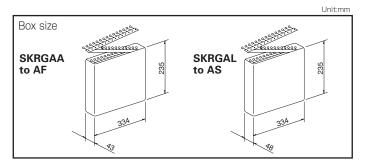
■ Product Line

Product No.	Operating	Operating direction	Operating life	Stem color	Stem height	Minimum ord	er unit (pcs.)
Floudet No.	force	Operating direction	(5mA 5V DC)	Sterri coloi	Sterri Height	Japan	Export
SKRGAAD010	1.27N		500,000 cycles	Black			
SKRGABD010	1.57N		300,000 cycles	White	h=4.3mm		
SKRGACD010	2.55N		200,000 cycles	Gray			
SKRGADD010	1.27N	- Top push	500,000 cycles	Black			
SKRGAED010	1.57N			300,000 Cycles	White	h=5mm	
SKRGAFD010	2.55N		200,000 cycles	Gray		2.000	2,000
SKRGALD010	1.27N		500,000 cycles	Black		2,000	2,000
SKRGAMD010	1.57N		500,000 Cycles	White	h=7mm		
SKRGAND010	2.55N		200,000 cycles	Gray			
SKRGAQD010	1.27N		500,000 cycles	Black			
SKRGARD010	1.57N		500,000 Gycles	White	h=9.5mm		
SKRGASD010	2.55N		200,000 cycles	Gray			

■ Packing Specifications

Radial Taping

Number of packages (pcs.)			Export package measurements	
1 box	1 case / Japan	1 case / export packing	(mm)	
2,000	0.000	SKRGAA to AF 353×506×244		
2,000 20,000	20,000	SKRGAL to AS 353×506×269		



Dimensions

Style

PC board mounting hole dimensions (Viewed from switch mounting face)

12.7

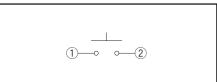
Stem

h
A
4.3
3.4
5
3.4
7
3.2
9.5
2.9

NI-+-

Please use 1.6mm thick PC boards.

■ Circuit Diagram



	Type			S	Sharp Feeling Typ	ie	,	
Type		Snap-in				Radial		
	Series	SKHL	SKHH	SKQJ	SKQB	SKRG	SKQK	SKRC
	Photo		STATE			• • •	***	888
	Features	_	_	_	_	Round terminal type	_	Round terminal type
	Water-proof	_	_	_	•	_	_	•
	Dust-proof	_	_	•	•	_	_	•
	IP standard	_	_	_	_	_	_	_
Operatir	Top push	_	_	_	_	•	•	•
directio		•	•	•	•	_	_	_
	W	7.3	7.5	7.5	11.5	10.0	□6.6	ø 9
Dimensio (mm)	ons D	7.22	7.85	7.85	11.9	φ 6.2		
(11111)	Н	4.3	7.4	7.3	11.3	See the relevant pages for respective product descriptions	5	13
Operation force coverage	2N to 3N ge 3N to 4N	1	1	1	\$	Ţ	1	1
	4N to 5N Travel (mm)		0.25		0.3		0.25	
	round terminal	•	•	_	_	_	_	_
Operating temperature range		-40°C 1	to +90°C	-20°C to +70°C	-40℃ to +95℃	-40℃ to +90℃	-20℃ to +70℃	−30°C to +85°C
А	utomotive use	•	•	_	•	•	_	_
	Life Cycle	* 2	*3	* 2	*2	*2	*2	*2
	Rating (max.) (Resistive load)	50mA 12V DC						
Electrical	Rating (min.) (Resistive load)		10µA 1V DC					
performance	Insulation resistance			100M	IΩ min. 100V DC	1min.		
	Voltage proof	250V AC 1min.						
Durability	Vibration	10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2 hours respectively						
Durability	Lifetime	Shall be in accordance with individual specification			S.			
	Cold	-40℃ 96h -30℃ 96h		-40°	C 96h	-30°C 96h	-40℃ 96h	
Environmental performance	Dry heat	90°C 96h 80°C 96h		80°C 96h	90°C	96h	80℃ 96h	90℃ 96h
	Damp heat	60%	C, 90 to 95%RI	H 96h	60°C, 90 to 95%RH 1,000h	60°C, 90 to	95%RH 96h	60°C, 90 to 95%RH 1,000h
	Page	195	197	202	204	251	253	254

 $\ensuremath{\mathsf{W}}$: Width. The most outer dimension excluding terminal portion.

 $\mathsf{D}:\mathsf{Depth}.$ The most outer dimension excluding terminal portion. H: Height. The minimum dimension if there are variances.

Notes

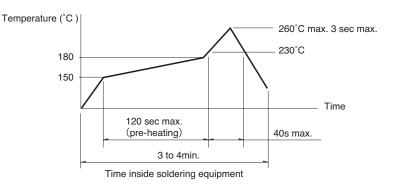
- 1. The automotive operating temperature range to be individually discussed upon request.
- 2. Indicates applicability to all products in the series.

TACT Switch™ Soldering Conditions

Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface).
 - A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



Notes

- The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others.
 The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

■ Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKHH, SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKQJ, SKQK, SKEG Series

Items	Condition
TLEMS	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	45s max.
Soldering temperature	255℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

■ Manual Soldering

Items	Condition
Soldering temperature	350℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360°C max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

Notes

- 1. Prevent flux penetration from the top side of the TACT Switch™.
- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)

